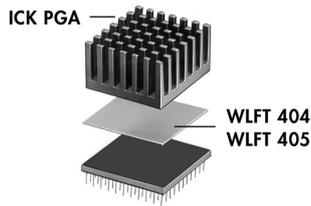


## Data sheet Product ICK PGA 15 x 15



Heatsinks and active heatsinks for processors>Heatsinks for PGA  
38,1 x 37,92 x 16,5 mm, for IC design PGA and others

### Features

way of fixation:	<ul style="list-style-type: none"> <li>• therm. conductive foil</li> <li>• therm. cond. adhesive</li> </ul>
socket:	universal
suitable for processor type:	universal
width:	38.1 mm
height:	16.51 mm
plate thickness:	3.5 mm
length:	37.92 mm
thermal resistance:	9.4 - 2.1 K/W
dissipation loss:	5.9 W
surface:	black anodised

### Technical Drawing

